Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	12 X 12 X 0.85 (7.4 EP)
Lead Count	88
Terminal Finish	100 Sn
MS Number	MS010673B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.20E-01	86.91	869100	33.15	331501
Thermosets	Epoxy & Phenol Resin	Proprietary	1.77E-02	12.78	127800	4.87	48747
Other inorganic materials	Carbon black	1333-86-4	4.28E-04	0.31	3100	0.12	1182
Subtotal			1.38E-01	100.00	1000000	38.14	381430

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.99 E-01	97.50	975000	55.04	550389
Copper & its alloys	Iron	7439-89-6	4.80 E-03	2.35	23500	1.33	13266
Copper & its alloys	Zinc	7440-66-6	2.45 E-04	0.12	1200	0.07	677
Copper & its alloys	Phosphorus	7723-14-0	6.13 E-05	0.03	300	0.02	169
Subtotal			2.04 E-01	100.00	1000000	56.45	564502

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.04 E-03	100.0	1000000	0.56	5645

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.85 E-03	100.0	1000000	1.06	10636

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.37 E-03	100.0	1000000	0.65	6535

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.89 E-03	100.0	1000000	2.73	27313

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.05 E-03	73.54	735400	0.29	2897
Other organic materials	Epoxy resin A	TS ref# 10013	1.05 E-04	7.35	73500	0.03	289
Others	Anhydride	TS ref# 10181	1.05 E-04	7.35	73500	0.03	289
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.19 E-05	2.94	29400	0.01	116
Other organic materials	Epoxy resin B	TS ref# 10237	4.19 E-05	2.94	29400	0.01	116
Others	Epoxy resin modifier	TS ref# 10038	4.19 E-05	2.94	29400	0.01	116
Others	Anhydride	TS ref# 10180	4.19 E-05	2.94	29400	0.01	116
Subtotal			1.43 E-03	100.0	1000000	0.39	3939

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.62 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary